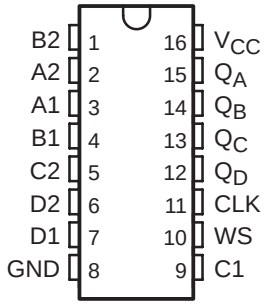
- **Selects One of Two 4-Bit Data Sources and Synchronously Stores Data With System Clock**
- **Applications:**
  - **Dual Source for Operands and Constants in Arithmetic Processor; Can Release Processor Register Files for Acquiring New Data**
  - **Implements Separate Registers Capable of Parallel Exchange of Contents, Yet Retains External Load Capability**
  - **Has Universal-Type Register for Implementing Various Shift Patterns, Including Compound Left-Right Capability**
- **Package Options Include Plastic Small-Outline (D) Packages and Standard Plastic (N) 300-mil DIPs**

D OR N PACKAGE
(TOP VIEW)



description

The SN74AS298A is a quadruple 2-input multiplexer with storage that provides essentially the equivalent functional capabilities of two separate MSI functions (SN74AS157 and ′AS175A) in a 16-pin package.

When the word-select (WS) input is low, word 1 (A1, B1, C1, D1) is applied to the flip-flops. A high input to WS causes the selection of word 2 (A2, B2, C2, D2). The selected word is clocked to the output terminals on the negative-going edge of the clock pulse.

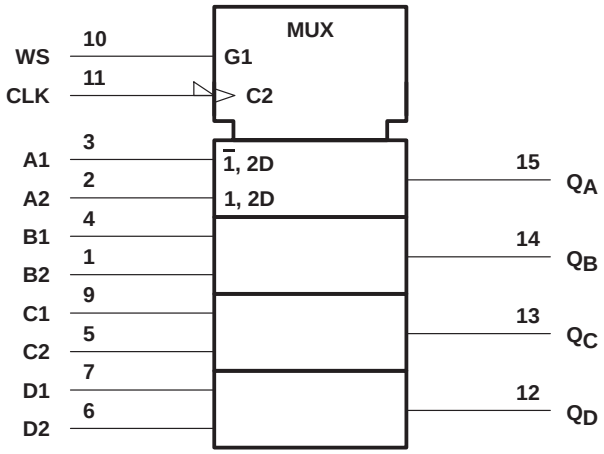
The SN74AS298A is characterized for operation from 0°C to 70°C.

FUNCTION TABLE

INPUTS		OUTPUTS†			
WS	CLK	Q_A	Q_B	Q_C	Q_D
L	↓	a1	b1	c1	d1
H	↓	a2	b2	c2	d2
X	H	Q_{A0}	Q_{B0}	Q_{C0}	Q_{D0}

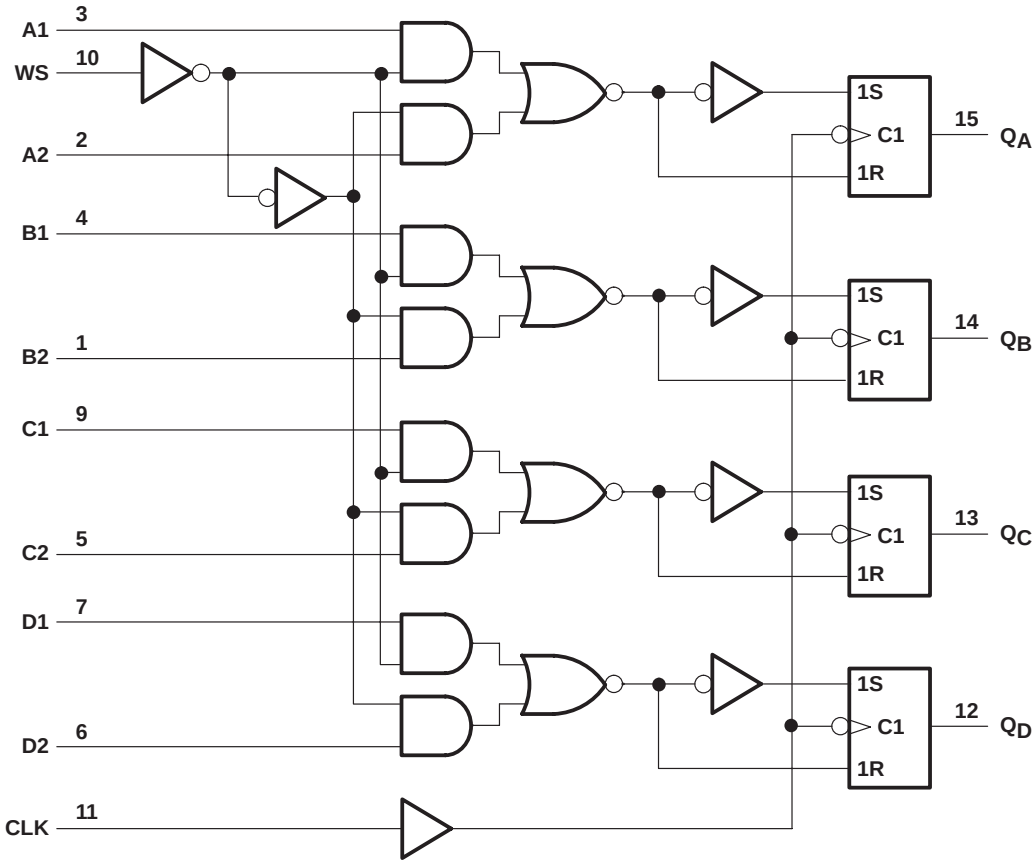
† a1, a2, etc. = the level of steady-state input at A1, A2, etc.
Q_{A0}, Q_{B0}, etc. = the level of Q_A, Q_B, etc. entered on the most recent ↓ transition of CLK

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} . . . . . 7 V
Input voltage, V_I . . . . . 7 V
Operating free-air temperature range, T_A . . . . . 0°C to 70°C
Storage temperature range . . . . . 65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
I_{OH}	High-level output current			−2	mA
I_{OL}	Low-level output current			20	mA
T_A	Operating free-air temperature	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP‡	MAX	UNIT
V_{IK}		V_{CC} = 4.5 V,	I_I = −18 mA			−1.2	V
V_{OH}		V_{CC} = 4.5 V to 5.5 V,	I_{OH} = −2 mA	V_{CC}−2			V
V_{OL}		V_{CC} = 4.5 V,	I_{OL} = 20 mA		0.35	0.5	V
I_I		V_{CC} = 5.5 V,	V_I = 7 V			0.1	mA
I_{IH}	WS	V_{CC} = 5.5 V,	V_I = 2.7 V			40	µA
	All others					20	
I_{IL}	WS	V_{CC} = 5.5 V,	V_I = 0.4 V			−0.75	mA
	All others					−0.5	
I_O§		V_{CC} = 5.5 V,	V_O = 2.25 V	−30		−112	mA
I_{CCH}		V_{CC} = 5.5 V			21	33	mA
I_{CCL}		V_{CC} = 5.5 V			22	36	mA

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
f_{clock}	Clock frequency		0	62	MHz
t_w	Pulse duration, CLK high or low		8		ns
t_{su}	$\overline{\text{Setup time before CLK}\downarrow}$	Data	4.5		ns
		WS	13		
t_h	Hold time after CLK↓	Data	3.5		ns
		WS	1		

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
f_{max}			62		MHz
t_{PLH}	CLK	Q	2	9	ns
t_{PHL}			1	11	

APPLICATION INFORMATION

This versatile multiplexer can be connected to operate as a shift register that can shift n places in a single clock pulse.

Figure 1 illustrates a BCD shift register that shifts an entire 4-bit BCD digit in one clock pulse.

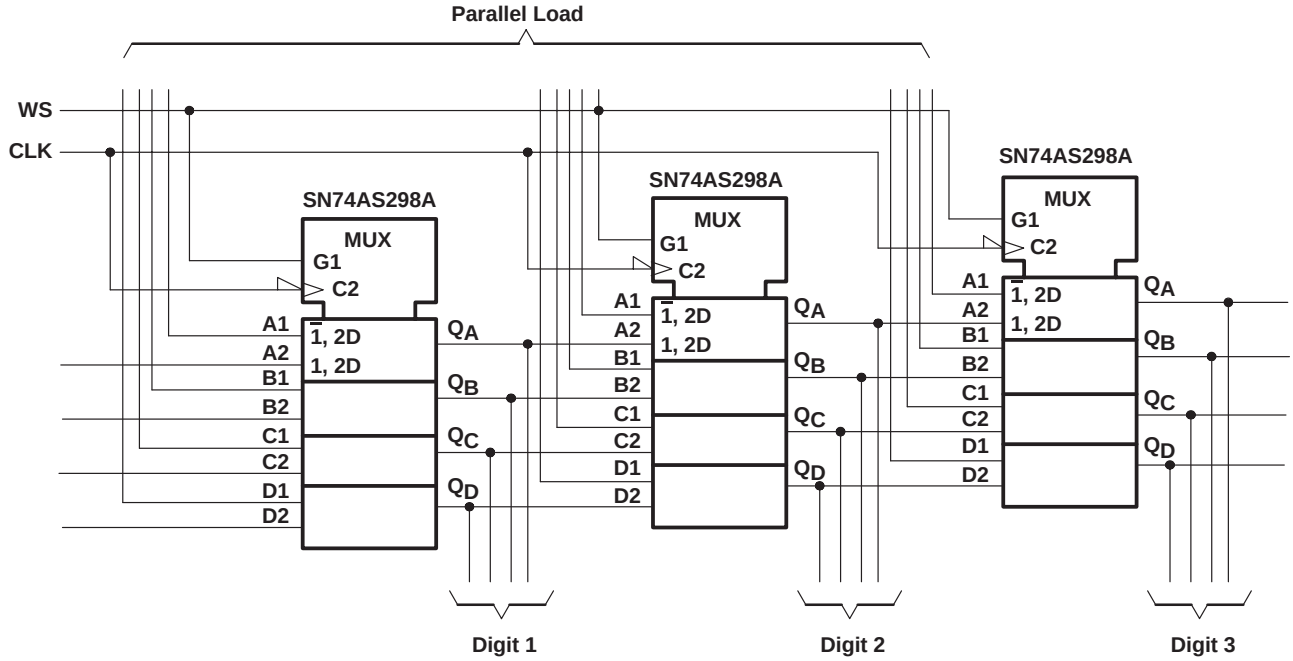


Figure 1. BCD Shift Register

When WS is high and the registers are clocked, the content of register 1 is transferred (shifted) to register 2, etc., effectively shifting the BCD digits one position. This application also retains a parallel-load capability, which means that new BCD data can be entered into the entire register with one clock pulse. This arrangement can be modified to perform the shifting of binary data for any number of bit locations.

Another function that can be implemented is a register designed specifically for supporting multiplier or division operations (see Figure 2).

When WS is low and the register is clocked, the outputs of the arithmetic/logic units (ALUs) are shifted one place. When WS is high and the registers are clocked, the data is shifted two places.

APPLICATION INFORMATION

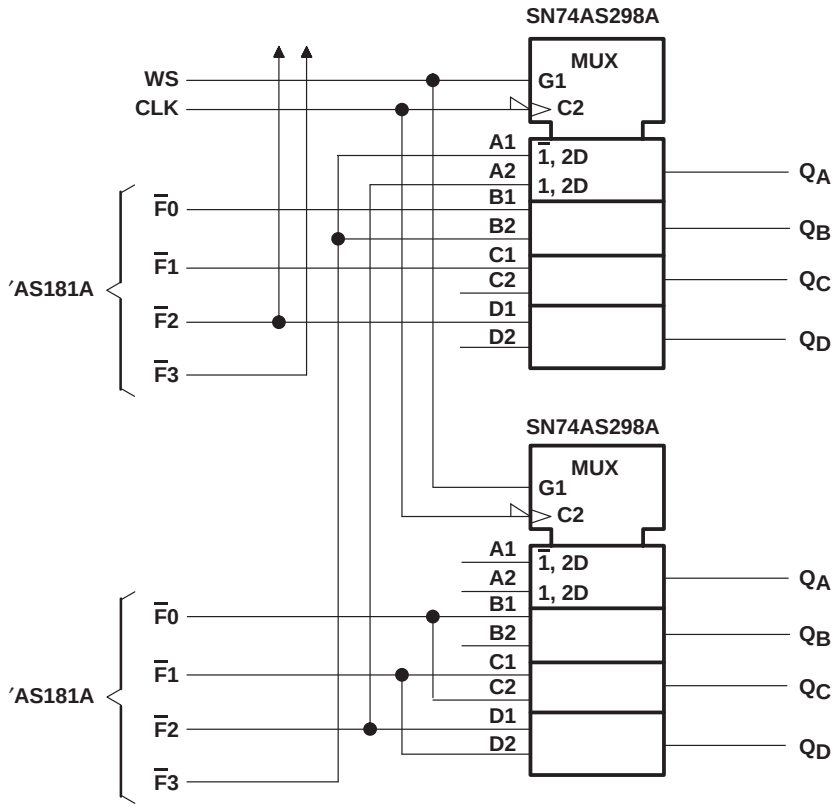
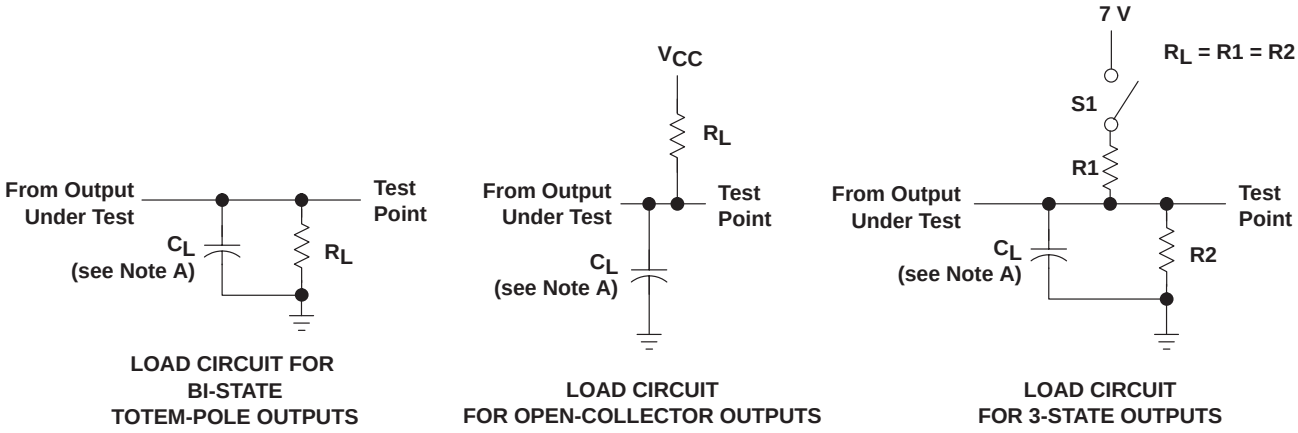


Figure 2. 1-Place/2-Place Shift Register

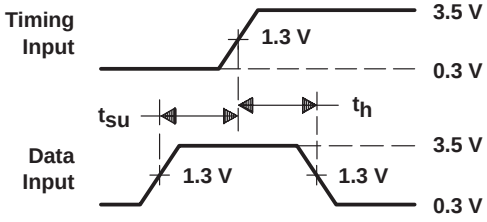
PARAMETER MEASUREMENT INFORMATION
SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



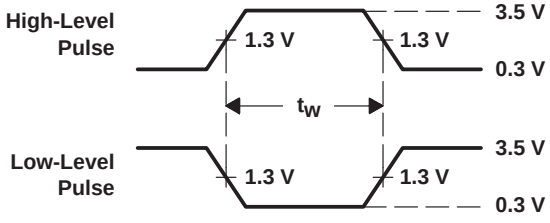
LOAD CIRCUIT FOR BI-STATE TOTEM-POLE OUTPUTS

LOAD CIRCUIT FOR OPEN-COLLECTOR OUTPUTS

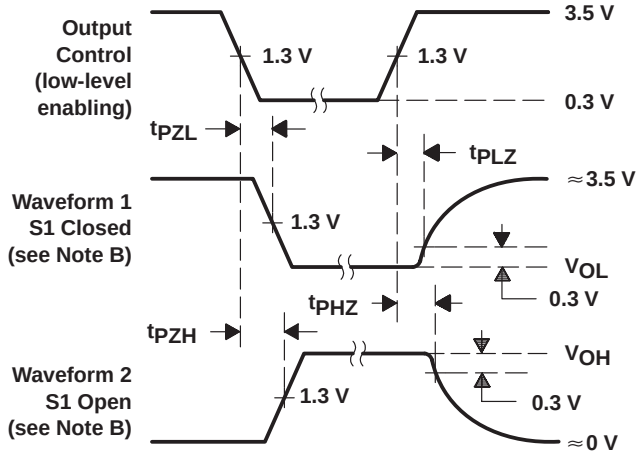
LOAD CIRCUIT FOR 3-STATE OUTPUTS



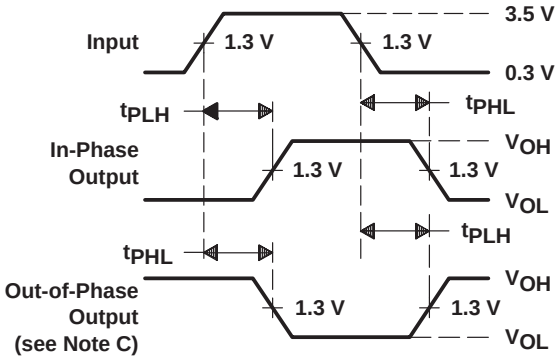
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PULSE DURATIONS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
D. All input pulses have the following characteristics: PRR ≤ 1 MHz, $t_r = t_f$ = 2 ns, duty cycle = 50%.
E. The outputs are measured one at a time with one transition per measurement.

Figure 3. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74AS298AD	Active	Production	SOIC (D) | 16	40 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	AS298A
SN74AS298AD.A	Active	Production	SOIC (D) | 16	40 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	AS298A
SN74AS298AN	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74AS298AN
SN74AS298AN.A	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74AS298AN

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

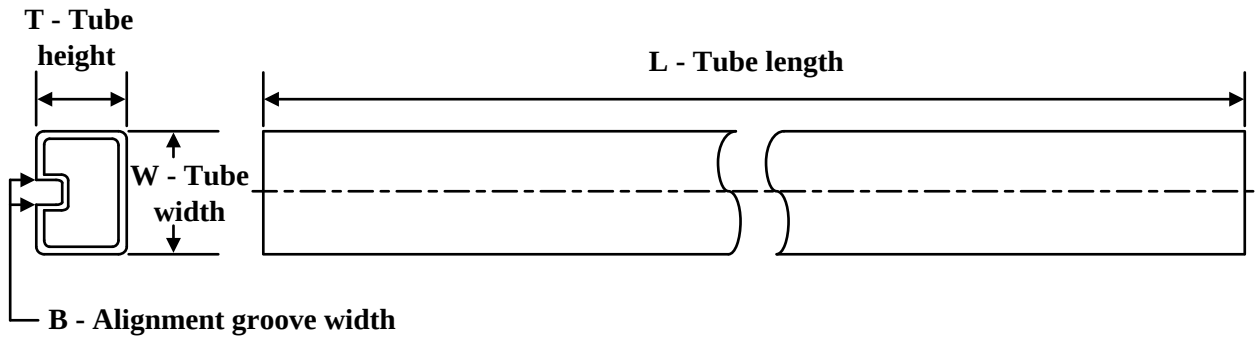
(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

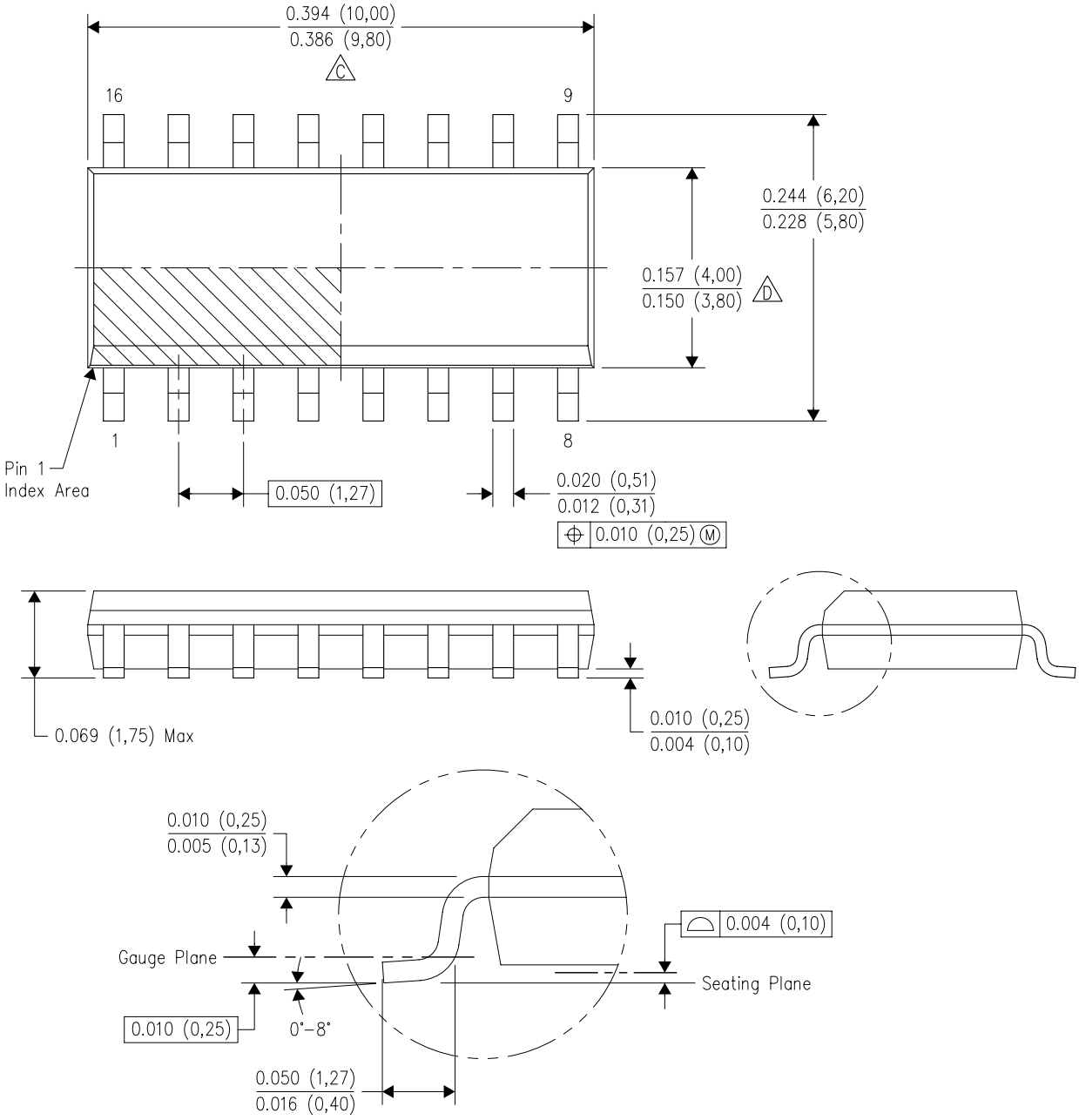
TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74AS298AD	D	SOIC	16	40	507	8	3940	4.32
SN74AS298AD.A	D	SOIC	16	40	507	8	3940	4.32
SN74AS298AN	N	PDIP	16	25	506	13.97	11230	4.32
SN74AS298AN	N	PDIP	16	25	506	13.97	11230	4.32
SN74AS298AN.A	N	PDIP	16	25	506	13.97	11230	4.32
SN74AS298AN.A	N	PDIP	16	25	506	13.97	11230	4.32

D (R–PDSO–G16) PLASTIC SMALL OUTLINE

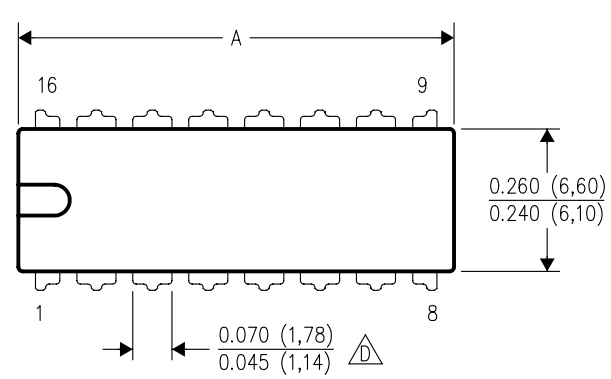


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

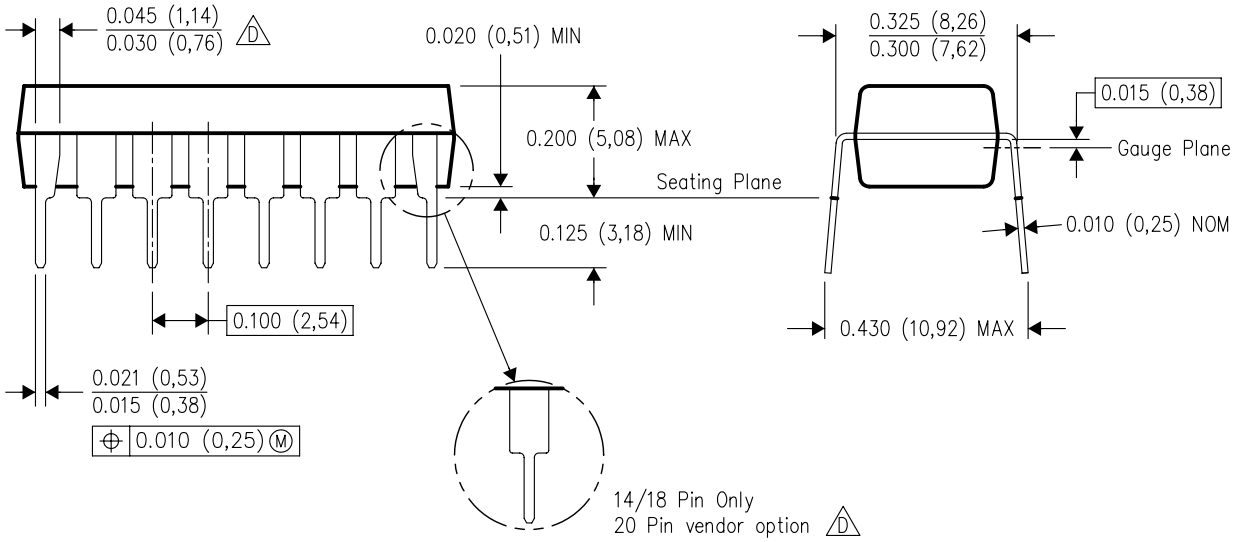
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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